

/ Descriptions

TO-263

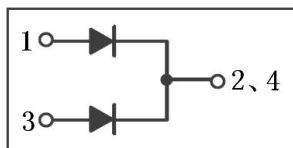
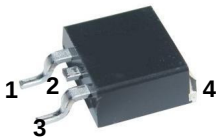
TO-263 Plastic package Schottky diode .

/ Features

Low forward voltage drop,low power losses,High efficiency operation.

/ Applications

For use in low voltage,high frequency inverters,free wheeling,and polarity protection applications.

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	V_{RRM} V_{RWM} V_{DC}	45	V
RMS Reverse Voltage	V_{RMS}	31.5	V
Average forward rectified Current	$I_{F(AV)}$	2×10	A
Non Repetitive Peak Surge Current	I_{FSM}	200	A
Thermal Resistance Junction to Case	R_{Jc}	2.2	/W
Junction and Storage Temperature Range	$T_j T_{stg}$	-55~+150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R = 1mA$ $T_a = 25$	45			V
Peak Forward Voltage	V_{FM}	$I_F = 5.0A$ $T_a = 25$			0.60	V
		$I_F = 5.0A$ $T_a = 125$			0.50	V
		$I_F = 10A$ $T_a = 25$			0.70	V
		$I_F = 10A$ $T_a = 125$			0.60	V
Instantaneous Reverse Current	I_R Note 1	$V_R = 45V$ $T_a = 25$			100	μA
		$V_R = 45V$ $T_a = 125$			15	mA

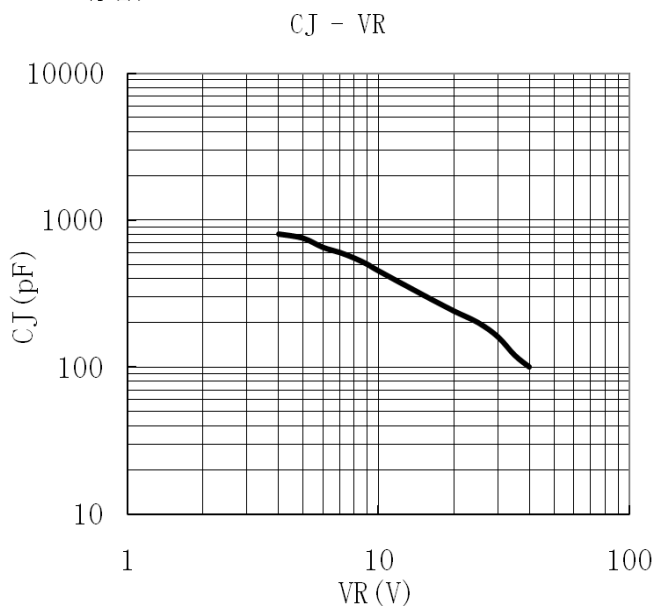
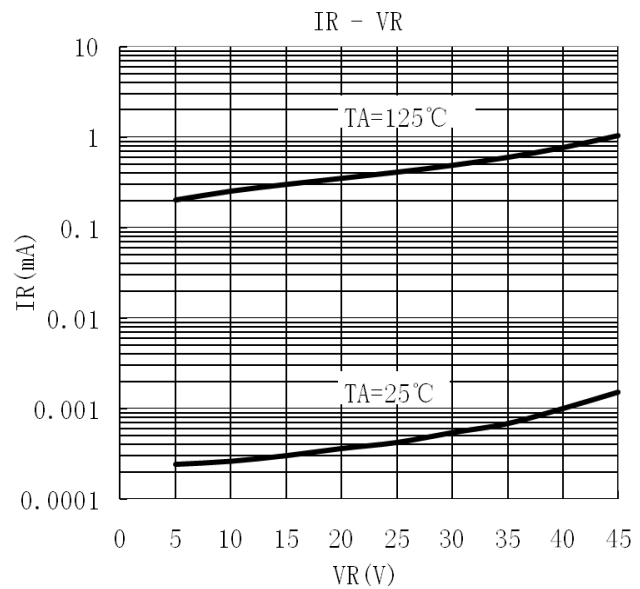
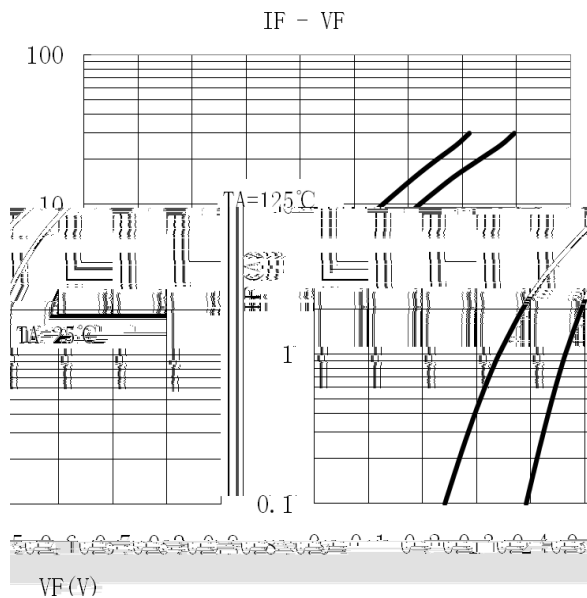
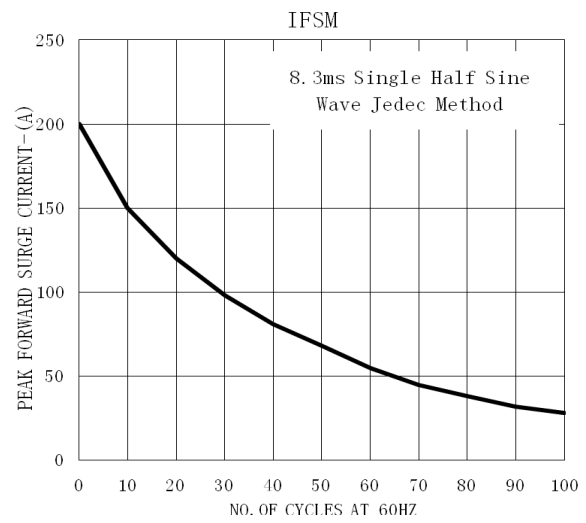
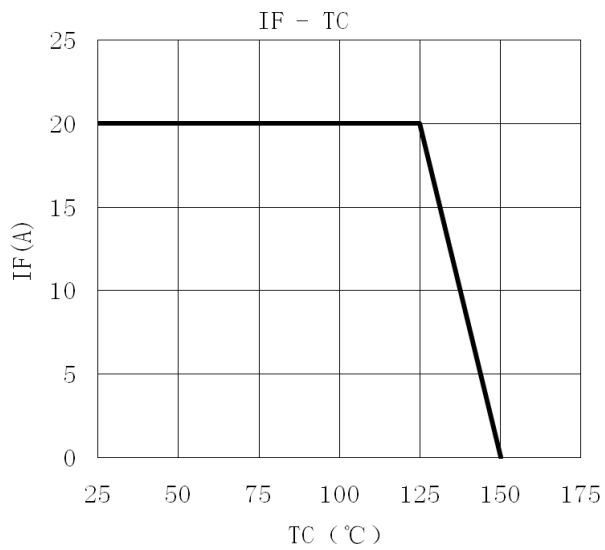
/Notes

1. /Short duration pulse test used to minimize self-heating effect.

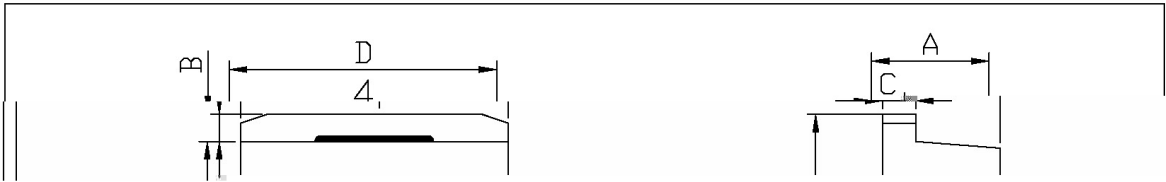
2. / Unless otherwise noted, values for the parameters of a single chip.



/ Electrical Characteristic Curve



/ Package Dimensions

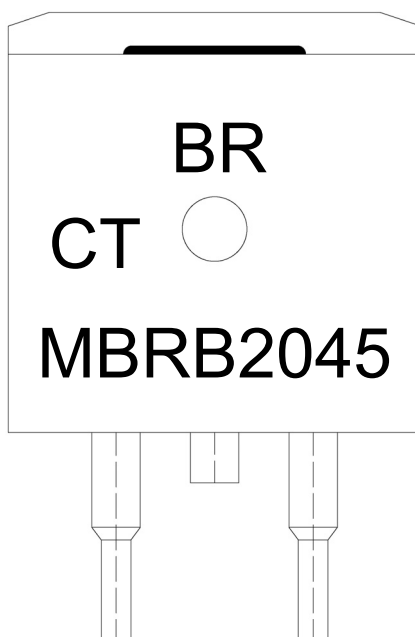


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74
b	0.70	0.90	e2	4.88	5.28
b1	1.15	1.35	L1	15.00	16.00
b2	0.40	0.60	L2	2.25	2.85
C	1.20	1.40	L3	1.20	1.60
D	9.80	10.20			



/ Marking Instructions



BR

MBRB2045

CT:

Note:

BR: Company Code

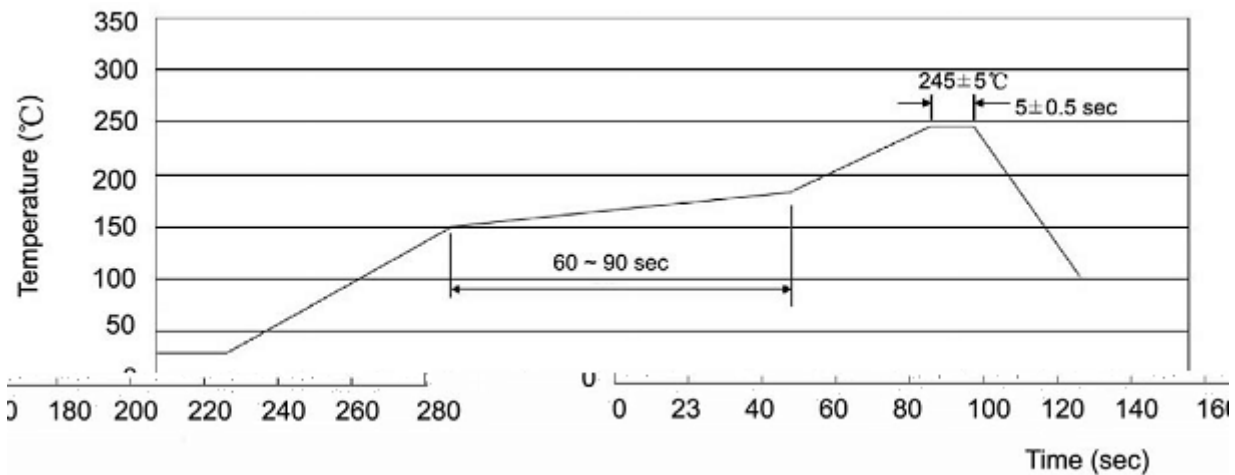
MBRB2045: Product Type.

CT: Internal Structure

****: Lot No. Code, code change with Lot No.



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		

/ TUBE

Package Type	Units					Dimension (unit mm ³)		